



## Materials Declaration Form

<b>IPC Form Type *</b>	1752 Distribute	<b>Version</b>	2
<b>Sectionals *</b>	Material Info Manufacturing Info	<b>Subsectionals *</b>	A-D
<i>* : Required Field</i>			

Supplier Information			
<b>Company Name *</b>	STMicroelectronics	<b>Response Date *</b>	2016-07-25
<b>Contact Name *</b>	Refer to Supplier Comment section		Refer to Supplier Comment section
<b>Authorized Representative *</b>	Giovanni Giacopello	<b>Representative Title</b>	ADG MD Champion
<b>Representative Phone *</b>	Refer to Supplier Comment section	<b>Representative Email *</b>	Refer to Supplier Comment section
<b>Supplier Comment</b>	Online Technical Support - STMicroelectronics : <a href="http://www.st.com/web/en/support/support.html">http://www.st.com/web/en/support/support.html</a>		

Uncertainty Statement			
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Legal Statement			
<b>Supplier Acceptance *</b>	true	<b>Legal Declaration *</b>	Standard
<b>Legal Statement</b>	<p>Supplier certifies that it gathered the provided information and such information is true and correct to the best of its knowledge and belief, as of the date that Supplier completes this form. Supplier acknowledges that Company will rely on this certification in determining the compliance of its products. Company acknowledges that Supplier may have relied on information provided by others in completing this form, and that Supplier may not have independently verified such information. However, in situations where Supplier has not independently verified information provided by others, Supplier agrees that, at a minimum, its suppliers have provided certifications regarding their contributions to the part(s), and those certifications are at least as comprehensive as the certification in this paragraph. If the Company and the Supplier enter into a written agreement with respect to the identified part(s), the terms and conditions of that agreement, including any warranty rights and/or remedies provided as part of that agreement, will be the sole and exclusive source of the Supplier's liability and the Company's remedies for issues that arise regarding information the Supplier provides in this form.</p>		

Product				
Mfr Item Number	Mfr Item Name	Version	Mfr Site	Date
VNL5300S5-E	RSKU*VNZ4ABC	A	SHENZHEN B/E	2016-07-25
Amount		UoM	Unit type	ST ECOPACK Grade
80.00		mg	Each	ECOPACK2

Manufacturing information				
J-STD-020 MSL Rating	Classification Temp	Nbr of Reflow Cycles		
3	260	3		
bulk Solder Termination	Terminal Plating	Terminal Base Alloy	Comment	
NAC	NiThPdAgAu	Copper Alloy		



Package Designator	Size	Nbr of instances	Shape	
DSO	4.9-6-1.75	8	GULL WING	
Comment	SO 08 STRIP SINGLE ISLAND 4+3+1			

QueryList : ROHS directive 2011/65/EU _ July 2011	
Query	Response
1 - Product(s) meets EU RoHS requirement without any exemptions	false
2 - Product(s) meets EU RoHS requirements except lead in solder and this usage may qualify under the lead in solder '7b' exemption (other selected exemptions may apply)	false
3 - Product(s) meets EU RoHS requirements by application of the selected exemption(s)	true
4 - Product(s) does not meet EU RoHS requirements and is not under exemptions	false
5 - Product(s) is obsolete, no information is available	false
6 - Product(s) is unknown, no information is available	false
Exemption Id.	Description
7a	Lead in high melting temperature type solders (i.e. lead- based alloys containing 85 % by weight or more lead)

QueryList : REACH-20th June 2016				
Query				Response
1 - Product(s) does not contain REACH Substances Of Very High Concern above the limits per the definition within REACH				true
CategoryLevel_Name	CategoryLevel_Threshold	amount in product (mg)	Application	ppm in product

Material Composition Declaration						Mfr Item Name	RSKU*VNZ4ABC					
Homogeneous Material	Material Group	Mass	UoM	Level	Substance Category	Substance	CAS	Exempt	Mass	UoM	Concentration in homogeneous material (ppm)	Concentration in product (ppm)
Die	Other inorganic materials	0.941	mg	supplier	die	Silicon (Si)	7440-21-3		0.895	mg	952178	11200
				supplier	metallization	Titanium (Ti)	7440-32-6		0.023	mg	24442	288
				supplier	Passivation	Silicon Nitride	12033-89-5		0.004	mg	4251	50
				supplier	Passivation	Silicon Oxide	7631-86-9		0.011	mg	11690	138
				supplier	back side metallization	Gold (Au)	7440-57-5		0.001	mg	1063	13
				supplier	back side metallization	Nickel (Ni)	7440-02-0		0.006	mg	6376	75
Leadframe	Copper & its alloys	30.109	mg	supplier	alloy	Copper (Cu)	7440-50-8		29.710	mg	986749	371375
				supplier	alloy	Iron (Fe)	7439-89-6		0.014	mg	465	175
				supplier	alloy	Iron Phosphide (FeP)	26508-33-8		0.025	mg	830	313
				supplier	metallization	Nickel (Ni)	7440-02-0		0.115	mg	3819	1438
				supplier	metallization	Palladium (Pd)	7440-05-3		0.006	mg	199	75
				supplier	metallization	Gold (Au)	7440-57-5		0.003	mg	100	38
				supplier	metallization	Silver (Ag)	7440-22-4		0.236	mg	7838	2950
				supplier	glue or tape	Silver (Ag)	7440-22-4		0.343	mg	905013	4288
				supplier	glue or tape	Isobornyl Methacrylate	7534-94-3		0.021	mg	55409	263
				supplier	glue or tape	Bismaleimide resin	Proprietary		0.015	mg	39578	188
Bonding wires	Other inorganic materials	0.136	mg	supplier	wire	Copper (Cu)	7440-50-8		0.136	mg	1000000	1700
Encapsulation	Other Organic Materials	48.436	mg	supplier	mold compound	Silica, vitreous	60676-86-0		41.945	mg	865988	524313
				supplier	mold compound	Epoxy Resin	25068-38-6		3.633	mg	75006	45413
				supplier	mold compound	Phenol Resin	29690-82-2		2.422	mg	50004	30275
				supplier	mold compound	Carbon black	1333-86-4		0.242	mg	4996	3025
				supplier	mold compound	Bismuth (Bi)	7440-69-9		0.194	mg	4006	2425